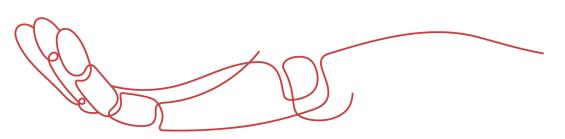




# **PRODUCT DATA SHEET**



To learn more about JGSEMI, please visit our website at







Datasheet

es Samples

Please note: Please check the JINGAO Semiconductor website to verify the updated device numbers. The most current and up-to-date ordering information can be found at www.jg-semi.cn. Please email any questions regarding the system integration to JINGAO\_questions@jgsemi.com.

2-Line Bi-directional ESD Diode

#### **Features**

- 420W peak pulse power (8/20µs)
- Protects two bi-directional lines
- Ultra low leakage: nA level
- Operating voltage: 24V
- Low clamping voltage
- Complies with following standards:
  - IEC 61000-4-2 (ESD) immunity test

Air discharge: ±30kV

Contact discharge: ±30kV

- IEC61000-4-4 (EFT) 40A (5/50ns)
- IEC61000-4-5 (Lightning) 9A (8/20μs)
- RoHS Compliant

## **Applications**

- Cellular Handsets and Accessories
- Notebooks and Handhelds
- Portable Instrumentation
- Set Top Box
- Industrial Controls
- Server and Desktop PC

## **Mechanical Characteristics**

Package: SOT-23

Lead Finish: Lead Free

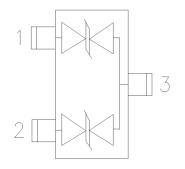
UL Flammability Classification Rating 94V-0

Quantity Per Reel:3,000pcs

Reel Size:7inch



**SOT-23** 



## Absolute Maximum Ratings(Tamb=25°C unless otherwise specified)

Parameter	Symbol	Value	Unit	
Peak Pulse Power (8/20μs)	Ppk	420	W	
Peak Pulse Current (8/20μs)	IPP	9	A	
ESD per IEC 61000-4-2 (Air)	VECD	±30	1-37	
ESD per IEC 61000-4-2 (Contact)	VESD	±30	kV	
Operating Temperature Range	TJ	-55 to +125	°C	
Storage Temperature Range	Tstg	-55 to +150	°C	

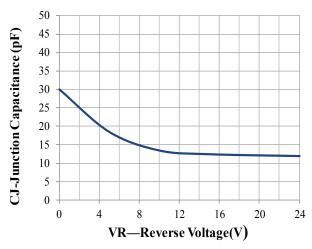


## **Electrical Characteristics**(TA=25°C unless otherwise specified)

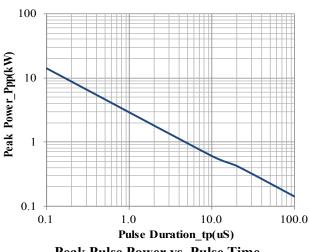
Parameter	Symbol	Test Condition	Min	Тур	Max	Unit
Reverse Working Voltage	VRWM				24	V
Breakdown Voltage	VBR	$I_T = 1 \text{mA}$	26	28.5	30. 5	V
Reverse Leakage Current	$I_R$	$V_{RWM} = 24V$			0.5	μΑ
Clamping Voltage	Vc	IPP = $1A (8 \times 20 \mu s \text{ pulse})$		35	40	V
Clamping Voltage	Vc	$I_{PP} = 9A (8 \times 20 \mu s \text{ pulse})$		45	58	V
Junction Capacitance	Сл	VR = 0V, f = 1MHz		30	50	pF



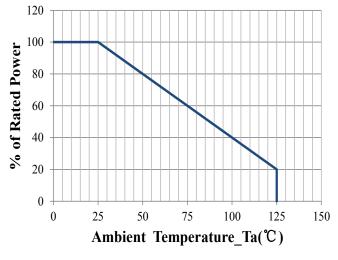
### **Characteristic Curves**



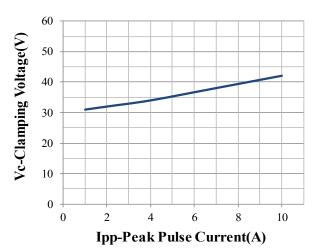
Junction Capacitance vs. Reverse Voltage



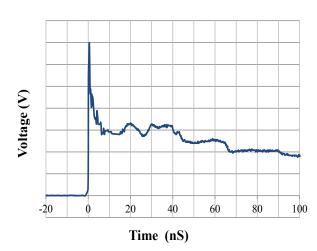
Peak Pulse Power vs. Pulse Time



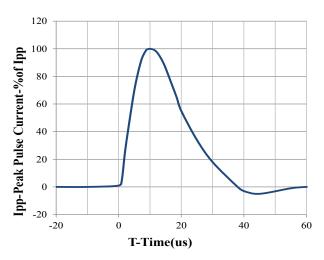
**Power Derating Curve** 



Clamping Voltage vs. Peak Pulse Current



IEC61000-4-2 Pulse Waveform

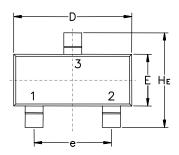


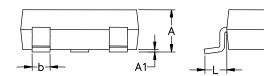
8 X 20us Pulse Waveform

# **NUP2105LT1G**



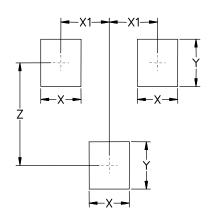
### **SOT-23 Package Outline & Dimensions**





0	Millimeters			Inches		
Symbol	Min.	Nom.	Max.	Min.	Nom.	Max.
Α	0.89	1.00	1.11	0.035	0.040	0.044
A1	0.01	0.06	0.10	0.001	0.002	0.004
b	0.37	0.44	0.50	0.15	0.18	0.020
С	0.09	0.13	0.18	0.003	0.005	0.007
D	2.80	2.90	3.04	0.110	0.114	0.120
E	1.20	1.30	1.40	0.047	0.051	0.055
е	1.78	1.90	2.04	0.070	0.075	0.081
L	0.35	0.54	0.69	0.014	0.021	0.029
H <sub>E</sub>	2.10	2.40	2.64	0.083	0.094	0.104

### **Soldering Footprint**



Symbol	Millimeters	Inches
х	0.80	0.031
X1	0.95	0.037
Υ	0.90	0.035
Z	2.00	0.079



#### **Attention**

- 1, Any and all JGSEMI products described or contained herein do not have specifications that can handle applications that require extremely high levels of reliability, such as life-support systems, aircraft's control systems, orother applic ations whose failure can be reasonably expected to result in serious physical or material damage. Consult with your JGSEMI representative nearest you before using any JGSEMI products described or contained herein in such applications.
- 2,JGSEMI assumes no responsibility for equipment failures that result from using products at values that exceed, even momentarily, rated values (such as maximum ratings, operating condition ranges, or other parameters) listed in products specifications of any and all JGSEMI products described or contained herein.
- 3, Specifications of any and all JGSEMI products described or contained herein stipulate the performance, characteristics, and functions of the described products in the independent state, and are not guarantees of the performance, characteristics, and functions of the described products as mounted in the customer's products or equipment. To ver ify symptoms and states that cannot be evaluated in an independent device, the customer should always evaluate and test devices mounted in the customer's products or equipment.
- 4,In the event that any or all JGSEMI products(including technical data, services) described or contained herein are controlled under any of applicable local export control laws and regulations, such products must not be exported wit hout obtaining the export license from the authorities concerned in accordance with the above law.
- 5, No part of this publication may be reproduced or transmitted in any form or by any means, electronic or mechanic al, including photocopying and recording, or any information storage or retrieval system, or otherwise, without the prior written permission of JGSEMI Semiconductor CO., LTD.
- 6, Any and all information described or contained herein are subject to change without notice due to product technology improvement, etc. When designing equipment, refer to the "Delivery Specification" for the JGSEMI product that you Intend to use.